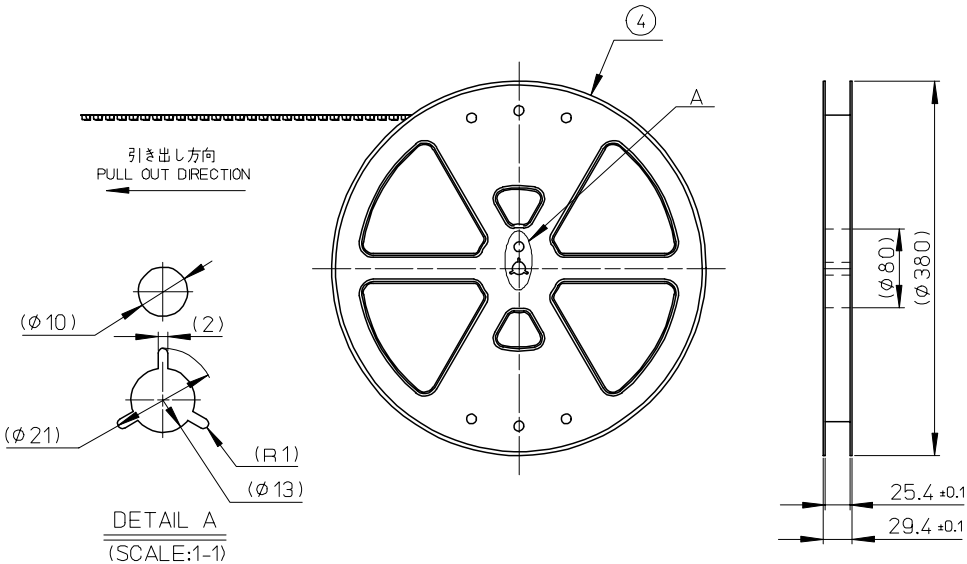


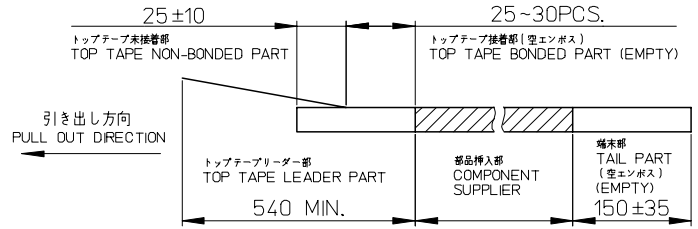
10 9 8 7 6 5 4 3 2 1

①	コネクタ CONNECTOR
②	エンボステープ EMBOSSSED TAPE
③	トップテープ TOP TAPE
④	リール REEL

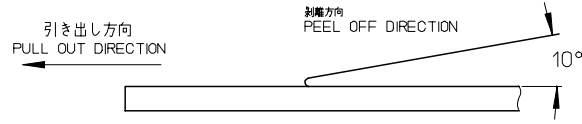


注記

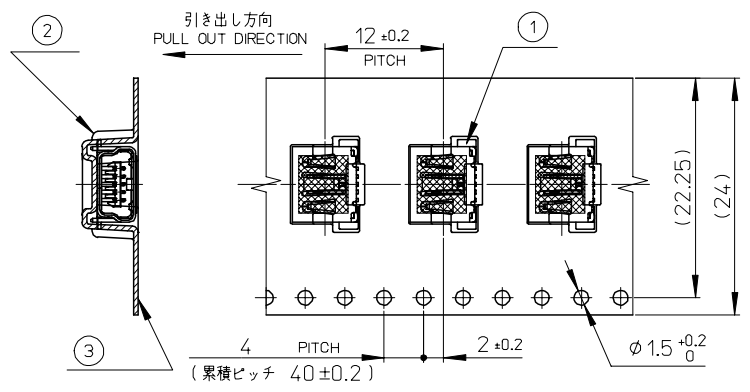
- コネクタ詳細は SD-51387-006を参照下さい。
REFER TO SD-51387-006
- 梱包数量: 1200個/リール
NUMBER OF CONNECTOR : 1200 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度: $0.6 \pm 0.35N$ ($60 \pm 35gf$)
<剥離速度: 300mm/min (参考)> (剥離方向は下図参照)
PEEL-OFF FORCE OF TOP TAPE : $0.6 \pm 0.35N$ ($60 \pm 35gf$)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
<PEEL-OFF SPEED : 300mm/min (REF.)>



- 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE : POLYPROPYLENE
トップテープ : ポリエステル, ポリエチレン
TOP TAPE : POLYESTER, POLYETHYLENE
リール : ポリスチレン
REEL : POLYSTYREN



エンボステープ内の製品の向き
DIRECTION OF PRODUCT
IN EMBOSSSED TAPE
(SCALE:2-1)

51387-0530	51387-***0
製品番号 MATERIAL No.	MODEL No.

新編作成 EC NO: J2005-0570 DRAWN: MSHINYAMA 2004/08/30 CHKD: HTAKASE 2004/08/30 APPR: JMIYAZAW 2004/09/02 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MSHINYAMA	DATE 04/07/18	TITLE EMBOSSSED TAPE PKG. FOR 51387-0539 -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/07/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY JMIYAZAWA	DATE 04/07/18	DOCUMENT NO. SD-51387-005	SHEET NO. 1 OF 1	
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

10 9 8 7 6 5 4 3 2 1

F

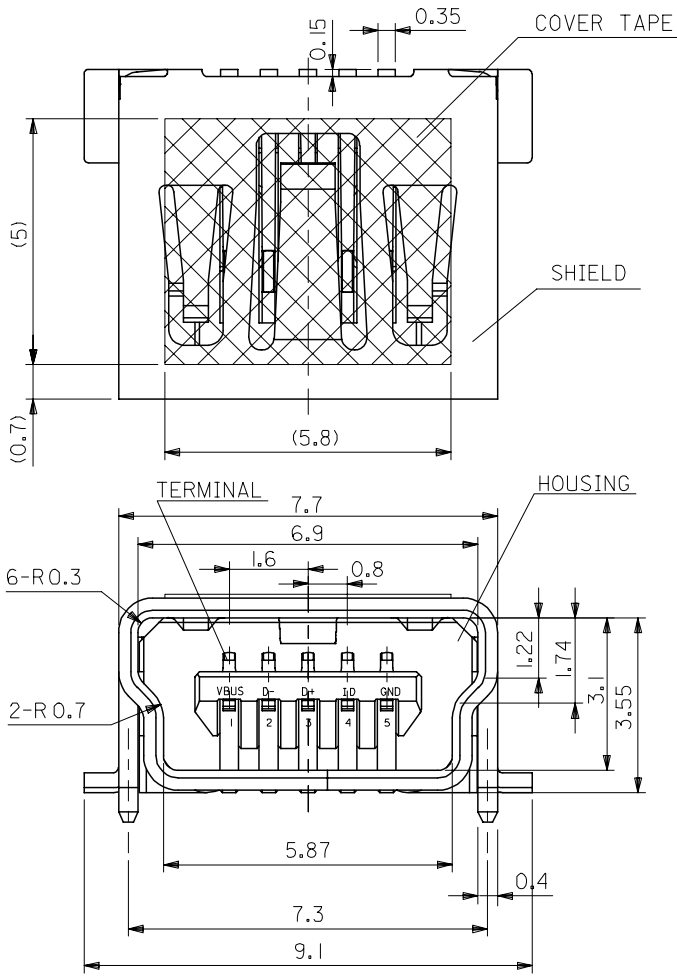
E

D

C

B

A



注記
NOTES

1. 材質

MATERIAL

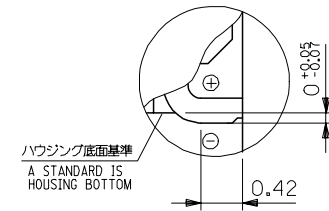
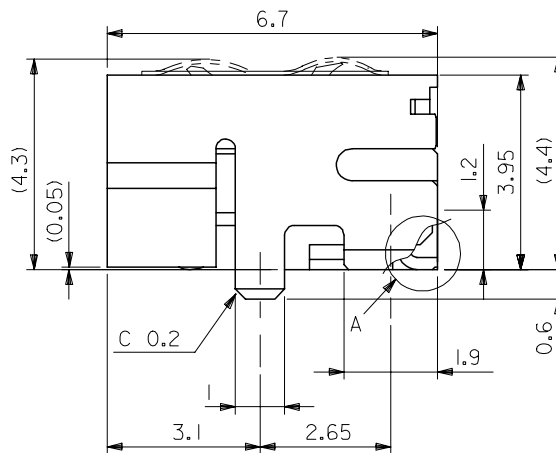
ハウジング:耐熱樹脂 ガラス充填,黒色,UL94V-0
 HOUSING:HEAT RESISTANT PLASTIC,
 GLASS FILLED,BLACK,UL94V-0
 ターミナル:銅合金 (t=0.25)
 TERMINAL:COPPER ALLOY(t=0.25)
 シールド:銅合金 (t=0.4)
 SHIELD :COPPER ALLOY(t=0.4)
 カバー テープ:ポリイミド (t=0.08)
 COVER TAPE:POLYIMIDE (t=0.08)

2. メッキ仕様

PLATING

ターミナル 接点部:金メッキ
 TERMINAL CONTACT AREA:GOLD
 半田付け部:錫メッキ
 SOLDER TAIL AREA:TIN
 下地部:ニッケルメッキ
 UNDER PLATING:NICKEL
 シールド:錫メッキ
 SHIELD :TIN
 下地部:ニッケル
 UNDER PLATING:NICKEL

3. 平坦度は0.1mm MAX.
 COPLANARITY 0.1mm MAX.



DETAIL A
 (SCALE 20:1)

5	51387-0539
極数 CKT.	製品番号 MATERIAL NO.

REVISED EC NO: J2007-2931 DRWN: AYOYAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APP: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/06/18	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	DOCUMENT NO. SD-51387-006			
	ANGULAR	±3 °	MATERIAL NO.		SHEET NO. 1 OF 2			
C	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

10 9 8 7 6 5 4 3 2 1

F

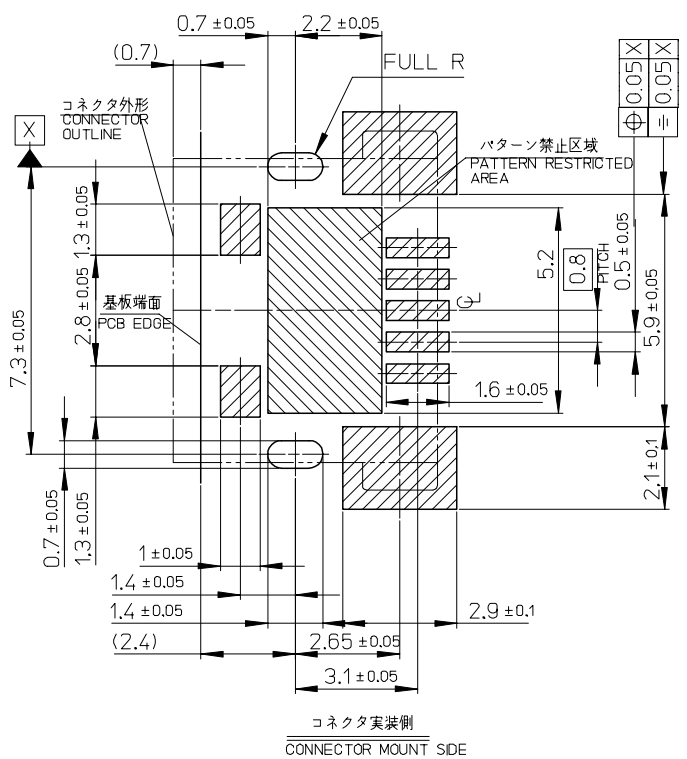
E

D

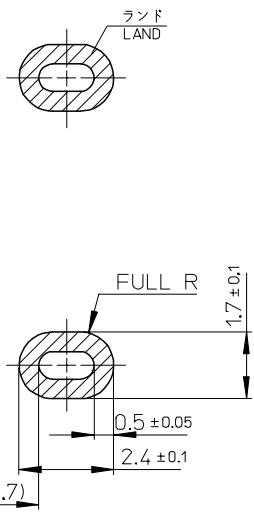
C

B

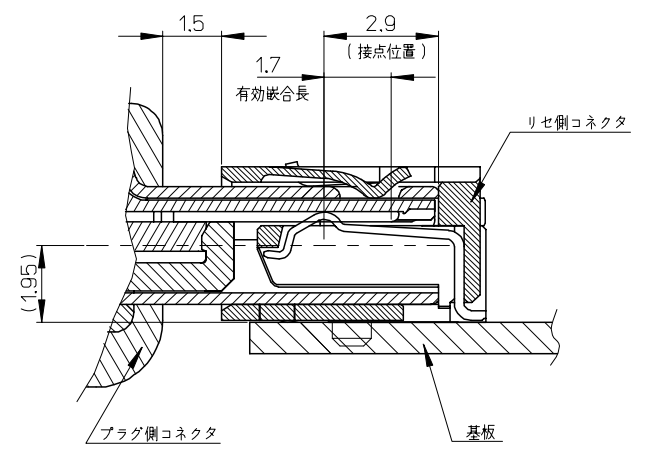
A



推奨基板寸法 (SCALE 8:1)
RECOMMENDED PCB PATTERN LAYOUT



逆側
REVERSE SIDE



コネクタ嵌合図
(SCALE 8:1)

REVISED EC NO: J2007-2931 DRWN: A0YAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APPR: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY MSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE-	
	10 OVER 30 UNDER	± 0.25	CHECKED BY HTAKASE	DATE 04/06/18	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	DOCUMENT NO. SD-51387-006	SHEET NO. 2 OF 2
	ANGULAR	± 3 °	MATERIAL NO. SEE SHEET 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				